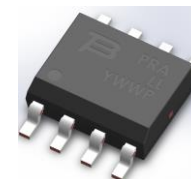


MATERIAL DECLARATION SHEET



Package Type	CDNBS08-SRDA15-4; CDNBS08-SRDA3.3-4; CDNBS08-SRDA05-4; CDNBS08-SRDA12-4				
Product Line	Semiconductor Products				
Compliance Date	January 09, 2025				
RoHS Compliant	Yes	Terminal	e3	MSL	1



No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.04726	Silica(Amorphous) A	60676-86-0	86.131	51.600	59.906
				Silica(Amorphous) B	7631-86-9	6.153	3.685	
				Epoxy Resin A	Proprietary	3.966	2.376	
				Epoxy Resin B	29690-82-2	1.615	0.968	
				Phenol Resin	Proprietary	1.605	0.960	
				Carbon Black	1333-86-4	0.529	0.317	
2	Leadframe	Copper Alloy	0.02821	Copper	7440-50-8	97.646	34.917	35.759
				Iron	7439-89-6	2.297	0.822	
				Phosphorus	7723-14-0	0.041	0.015	
				Zinc	7440-66-6	0.010	0.003	
		Silver Plating	0.00033	Silver	7440-22-4	100.000	0.418	0.418
3	Chip	Silicon	0.00116	Silicon	7440-21-3	90.458	1.339	1.470
				Nickel	7440-02-0	6.052	0.090	
				Aluminum	7429-90-5	3.115	0.035	
				Gold	7440-57-5	0.375	0.006	
4	Bond Wires	Gold	0.00034	Gold	7440-57-5	99.990	0.4305	0.431
				Non - Au element	Proprietary	0.010	0.0005	
5	Die Attach	Silver Epoxy	0.00028	Silver	7440-22-4	96.984	0.3436	0.355
				Epoxy resin A	9003-36-5	1.805	0.007	
				Epoxy Resin B	Proprietary	0.662	0.0023	
				Phenol Resin	Proprietary	0.457	0.0017	
6	Lead Finish	Matte Tin	0.00131	Tin	7440-31-5	100.000	1.661	1.661
		Total Weight	0.07889					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.